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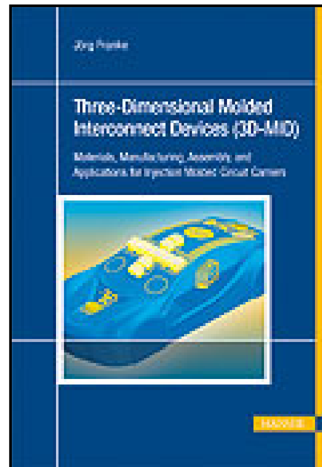

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Three-Dimensional Molded Interconnect Devices (3D-MID)

Materials, Manufacturing, Assembly and Applications for Injection Molded Circuit Carriers

Herausgegeben von Jörg Franke

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